



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130304000
Qualification of ASESH as Additional Assembly/Test Site
for BQ2409xDGQ device (include Au wire to Cu wire)
Change Notification / Sample Request

Date: 3/13/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130304000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
BQ24090DGQT	null
BQ24091DGQT	null
BQ24092DGQT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130304000	PCN Date:	03/13/2013
Title:	Qualification of ASES as Additional Assembly/Test Site for BQ2409xDGQ device (include Au wire to Cu wire)		
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037
		Dept:	Quality Services
Proposed 1st Ship Date:	06/13/2013	Estimated Sample Availability:	Date Provided at Sample request
Change Type:			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>		<input checked="" type="checkbox"/>	Assembly Materials
<input type="checkbox"/>		<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
PCN Details			
Description of Change:			
Qualification of ASES as additional assembly and test site for BQ2409xDGQ device (include Au wire to Cu wire). Assembly differences are shown in the following table:			
	NS2	ASES	
Wire	GZ0017 (1.0 Mil Au)	CW1000004 (1.0 Mil Cu)	
Mold compound	CZ0094	EN2000515	
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.			
Reason for Change:			
Continuity of Supply			
1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties			
2) Maximize flexibility within our Assembly/Test production sites.			
3) Cu is easier to obtain and stock			
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):			
None			
Changes to product identification resulting from this PCN:			
Assembly Site			
NS2 Thailand	Assembly Site Origin (22L)	ASO: NS2	
ASE Shanghai (ASES)	Assembly Site Origin (22L)	ASO: ASH	
Sample product shipping label (not actual product label)			
			
			
(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS			

Device Marking

YM \T/ O {CUST1}

\T/ = TI
YM = YEAR /MONTH DATE CODE
O = PIN 1 DIMPLE

Topside Device marking:

Assembly site code for NS2 = B

Assembly site code for ASESH = A

Product Affected:

BQ24090DGQR	BQ24092DGQR	BQ24093DGQR	BQ24095DGQR
BQ24090DGQT	BQ24092DGQT	BQ24093DGQT	BQ24095DGQT

Qualification Data : Approved 07/19/2011

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle 1: TPS40009DGQ (MSL1-260C)**Package Construction Details**

Assembly Site:	ASE Shanghai	Mold Compound:	EN2000515
# Pins-Designator, Family:	10-DGQ, MSOP	Mount Compound:	EY1000063
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	1.0 Mil Dia. Cu

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size / Fail
Electrical Characterization	-	Pass
**Steady-state Life Test	125C (1000 Hrs)	76/0
Manufacturability Qualification (MQ)	Assembly MQ	Pass

**- Preconditioning sequence: Level 1-260C.

Qual Vehicle 2: TPS62040DGQ (MSL1-260C)**Package Construction Details**

Assembly Site:	ASE Shanghai	Mold Compound:	EN2000515
# Pins-Designator, Family:	10-DGQ, MSOP	Mount Compound:	EY1000063
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	1.0 Mil Dia. Cu

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot3
Electrical Characterization	-	Pass	-	-
**Biased HAST	130C/85%RH (96 Hours)	77/0	77/0	77/0
**Temp Cycle, -65C/150C	500 Cycles	77/0	77/0	77/0
**High Temp Storage Bake	150C (1000 Hrs)	76/0	77/0	77/0
Manufacturability Qualification	Assembly MQ	Pass	Pass	Pass
X-ray	(top side only)	5/0	5/0	5/0
Moisture Sensitivity	Level 1, 260C peak +5/-0C	12/0	12/0	12/0

**- Preconditioning sequence: Level 1-260C.

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com